

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>OhHan Kim</td> <td>06/04/2008</td> </tr> <tr> <td>SeungWon Kim</td> <td>06/04/2008</td> </tr> <tr> <td>JoungUn Park</td> <td>06/04/2008</td> </tr> </tbody> </table>		Name	Execution Date	OhHan Kim	06/04/2008	SeungWon Kim	06/04/2008	JoungUn Park	06/04/2008
Name	Execution Date								
OhHan Kim	06/04/2008								
SeungWon Kim	06/04/2008								
JoungUn Park	06/04/2008								
RECEIVING PARTY DATA									
Name:	STATS ChipPAC, Ltd.								
Street Address:	10 Ang Mo Kio Street 65								
Internal Address:	#05-17/20 Techpoint								
City:	Singapore								
State/Country:	SINGAPORE								
Postal Code:	569059								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12136682</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12136682				
Property Type	Number								
Application Number:	12136682								
CORRESPONDENCE DATA									
Fax Number:	(602)229-5690								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	602-229-5290								
Email:	moneill@quarles.com								
Correspondent Name:	Robert D. Atkins								
Address Line 1:	QUARLES & BRADY LLP								
Address Line 2:	TWO NORTH CENTRAL AVENUE								
Address Line 4:	PHOENIX, ARIZONA 85004-2391								
ATTORNEY DOCKET NUMBER:	125155.00108								
NAME OF SUBMITTER:	Robert D. Atkins								
Total Attachments: 3									

CH \$40.00 12136682

source=Assignments#page1.tif
source=Assignments#page2.tif
source=Assignments#page3.tif

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, OHHAN KIM of South Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING SHIELDING LAYER GROUNDED THROUGH METAL PILLARS FORMED IN PERIPHERAL REGION OF THE SEMICONDUCTOR DIE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00108, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above -identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the a bove-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Ohhan Kim

Signature for OHHAN KIM

Witnessed on this date:

June 4, 2008

Signature of Witness:

HA SangWoo

Printed Name of Witness:

HA SangWoo

Address of Witness:

7-59 Yang-gae 1 Dong, Sucho-gu, Seoul, Korea

QBACTIVE\6233954.1

ASSIGNMENT AND AGREEMENT


For good and valuable consideration, the receipt of which is hereby acknowledged, I, SEUNGWON KIM of South Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING SHIELDING LAYER GROUNDED THROUGH METAL PILLARS FORMED IN PERIPHERAL REGION OF THE SEMICONDUCTOR DIE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00108, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.



Signature for SEUNGWON KIM

Witnessed on this date: Jun. 04 '08

Signature of Witness: 

Printed Name of Witness: Choi Dae Sik

Address of Witness: San 136-1, Ami-ri, Bubal-eub,
Icheon-si Kyongki-do, 447-701 Korea

QBACTIVE\6235029.1

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, JOUNGUN PARK of South Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING SHIELDING LAYER GROUNDED THROUGH METAL PILLARS FORMED IN PERIPHERAL REGION OF THE SEMICONDUCTOR DIE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00108, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Joungun Park

Signature for JOUNGUN PARK

Witnessed on this date: June 4 2008

Signature of Witness: *Lee Sang Ho*

Printed Name of Witness: Lee Sang Ho

Address of Witness: San 136-1, Ami-ri, Bubal-eub, Icheon-si, Kyungki-do, 467-701 Korea

OBACTIVE\6235058.1